

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4719555

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SOTARO OHARA	11/19/2017
KATSUYUKI TANAKA	11/20/2017
KATSUMI TAKAOKA	11/20/2017
KEITA IZUMI	11/20/2017
SUGURU HOUCHI	11/22/2017
GAJU HIDAI	11/20/2017
YUTAKA TAKAGI	11/16/2017
HIDEKI TAKAHASHI	11/17/2017
HIDEKI AWATA	11/17/2017
YASUSHI KATAYAMA	11/20/2017
NAOKI YOSHIMUCHI	11/20/2017
TOSHIMASA SHIMIZU	11/20/2017
RECEIVING PARTY DATA	
Name:	SONY SEMICONDUCTOR SOLUTIONS CORPORATION
Street Address:	4-14-1 ASAHI-CHO
Internal Address:	ATSUGI-SHI
City:	KANAGAWA
State/Country:	JAPAN
Postal Code:	2430014
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15577183
CORRESPONDENCE DATA	
Fax Number:	(312)803-4960
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	docketing@chiplawgroup.com
Correspondent Name:	CHIP LAW GROUP
Address Line 1:	155 N WACKER DR
Address Line 2:	SUITE 4250

PATENT

Address Line 4: CHICAGO, ILLINOIS 60606	
ATTORNEY DOCKET NUMBER:	SP363181US00
NAME OF SUBMITTER:	PRAMOD CHINTALAPOODI
SIGNATURE:	/Pramod Chintalapoodi/
DATE SIGNED:	12/05/2017
Total Attachments: 12 source=SP363181US00_Assignments#page1.tif source=SP363181US00_Assignments#page2.tif source=SP363181US00_Assignments#page3.tif source=SP363181US00_Assignments#page4.tif source=SP363181US00_Assignments#page5.tif source=SP363181US00_Assignments#page6.tif source=SP363181US00_Assignments#page7.tif source=SP363181US00_Assignments#page8.tif source=SP363181US00_Assignments#page9.tif source=SP363181US00_Assignments#page10.tif source=SP363181US00_Assignments#page11.tif source=SP363181US00_Assignments#page12.tif	

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE**

Title of
Invention

SIGNAL PROCESSING APPARATUS AND METHOD

As the below named inventor, I hereby declare that:

This declaration
is directed to:

☐

The attached application, or

☒

United States application or PCT international application number PCT/JP2016/065025

filed on 2016/05/20

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

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legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency
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legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and
in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to
any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American
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adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the
United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters
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this assignment and sale.

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not more than five (5) years, or both.

LEGAL NAME OF INVENTOR

Inventor: SOTARO OHARA

Date: 2017 / 11 / 19

Signature: Sotaro Ohara

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LEGAL NAME OF INVENTOR

Inventor: KATSUYUKI TANAKA

Date: November 20, 2017

Signature: Katsuyuki Tanaka

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LEGAL NAME OF INVENTOR

Inventor: KATSUMI TAKAOKA

Date: November 20, 2017

Signature: Katsumi Takaoka

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LEGAL NAME OF INVENTOR

Inventor: KEITA IZUMI

Date: November 20, 2017

Signature: Keita Izumi

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LEGAL NAME OF INVENTOR

Inventor: SUGURU HOUCHI

Date: 2017/11/22

Signature: SUGURU HOUCHI

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LEGAL NAME OF INVENTOR

Inventor: GAKU HIDAI

Date: November 25th, 2017

Signature: Gaku Hida

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Inventor: YUTAKA TAKAGI

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Date: November 17 2017

Signature: Hideki Takahashi

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN
APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE**

Title of
Invention

SIGNAL PROCESSING APPARATUS AND METHOD

As the below named inventor, I hereby declare that:

This declaration
is directed to:

☐ The attached application, or

☒ United States application or PCT international application number PCT/IP2016/065025
filed on 2016/05/20

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

WHEREAS, SONY SEMICONDUCTOR SOLUTIONS CORPORATION, with offices at
4-14-1 Asahi-cho, Atsugi-shi, Kanagawa, Japan (hereinafter referred to as ASSIGNEE), is desirous of
acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar
legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency
of which are hereby acknowledged, I by these presents do hereby assign, sell and transfer unto said ASSIGNEE, its successors, assigns, and
legal representatives, the entire right, title and interest in said invention, said application, including any divisions and continuations thereof, and
in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to
any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American
Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America
adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the
United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue said United States Letters
Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its
designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further
remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of
the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for
application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters
Patent which may be granted for my aforesaid invention, as said ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said
application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will
testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with
this assignment and sale.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of
not more than five (5) years, or both.

LEGAL NAME OF INVENTOR

Inventor: HIDEKI AWATA

Date: November 17, 2017

Signature: Hideki Awata

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LEGAL NAME OF INVENTOR

Inventor: YASUSHI KATAYAMA

Date: November 20, 2017

Signature: Yasushi Katayama

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LEGAL NAME OF INVENTOR

Inventor: NAOKI YOSHIMUCHI

Date: November 20, 2017

Signature: Naoki Yoshimochi

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LEGAL NAME OF INVENTOR Inventor: <u>TOSHIMASA SHIMIZU</u> Date: <u>November 20, 2017</u> Signature: <u>Toshimasa Shimizu</u> <u>November 20, 2017 T.S.</u>	